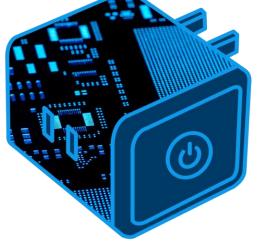
Smart Plug

Solution Proposal by Toshiba









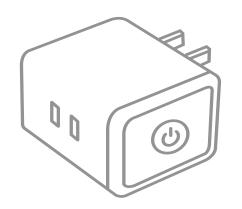




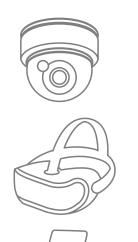








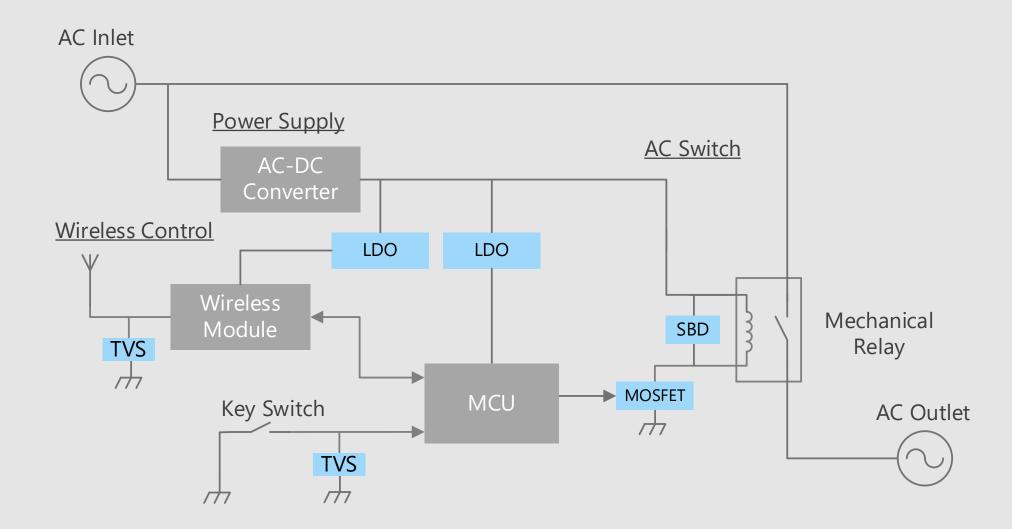
Toshiba Electronic Devices & Storage Corporation provides comprehensive device solutions to customers developing new products by applying its thorough understanding of the systems acquired through the analysis of basic product designs.



Block Diagram

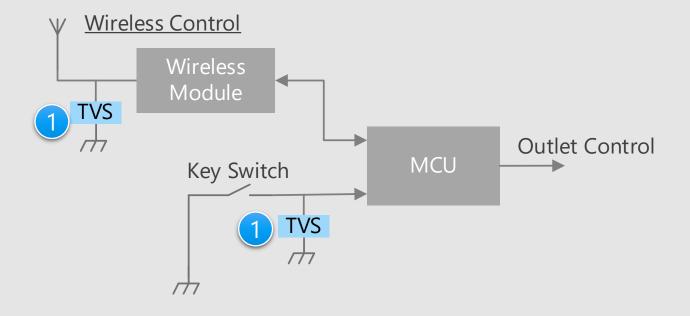
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Smart Plug Overall block diagram



Smart Plug Detail of wireless and key switch section

Wireless and key switch input circuit



Criteria for device selection

 Since components such as key switches and antennas which may be exposed to the outside environment, ESD protection circuitry may be required.

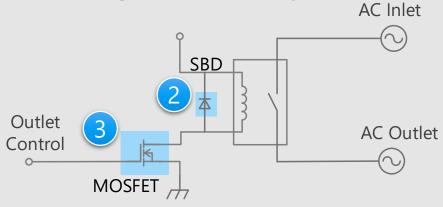
Proposal from Toshiba

 Prevent circuit malfunctions by absorbing electrostatic discharge (ESD) from external terminals
 TVS diode

^{*} Click on the blue circled numbers above to view detailed descriptions.

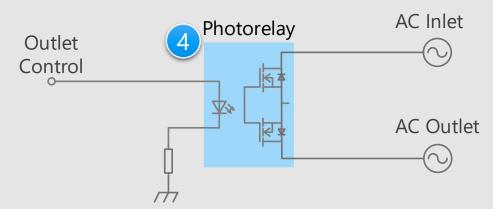
Smart Plug Details of AC switch section (1)

AC switch circuit using mechanical relay



SBD: Schottky barrier diode

AC switch circuit using photorelay (less than 0.3 A)



Criteria for device selection

- Schottky barrier diodes are suitable for freewheeling diodes used in inductive loads such as relays.
- Low power AC switches can be realized using photorelays.

Proposals from Toshiba

- Diodes suitable for freewheeling diodes
 Schottky barrier diode
- Small package and low on-resistance MOSFET

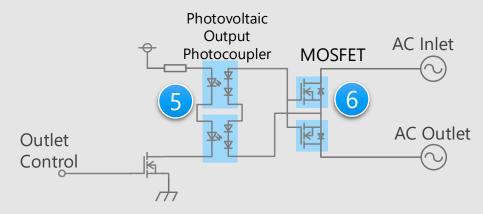
Small signal MOSFET

Designed for high AC isolation voltage
 Photorelay

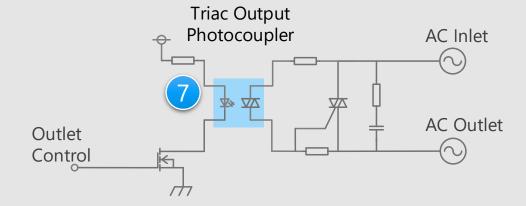
^{*} Click on the blue circled numbers above to view detailed descriptions.

Smart Plug Details of AC switch section (2)

AC switch circuit using photovoltaic output photocouplers and MOSFETs (around 0.3 A to 1 A)



AC switch circuit using triac and triac output photocouplers (1 A or more)



^{*} Click on the blue circled numbers above to view detailed descriptions.

Criteria for device selection

- Isolated AC switch can be realized using a MOSFET driven by a photovoltaic output photocoupler.
- AC switch can be realized using a triac driven by a triac output photocoupler.

Proposals from Toshiba

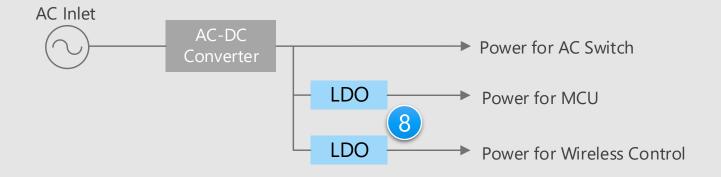
- Photocoupler for direct MOSFET driving
 - Photovoltaic output photocoupler
- Suitable for high efficiency power switching
 DTMOSIV Series MOSFET
- Photocoupler suitable for AC control
 Triac output photocoupler





Smart Plug Detail of power supply

Power supply circuit



Criteria for device selection

 For the power supply of an IC including an analog circuit such as wireless control, a low noise power supply is required for stable operation of the set.

Proposal from Toshiba

Supply the power with low noise
 Small surface mount LDO regulator

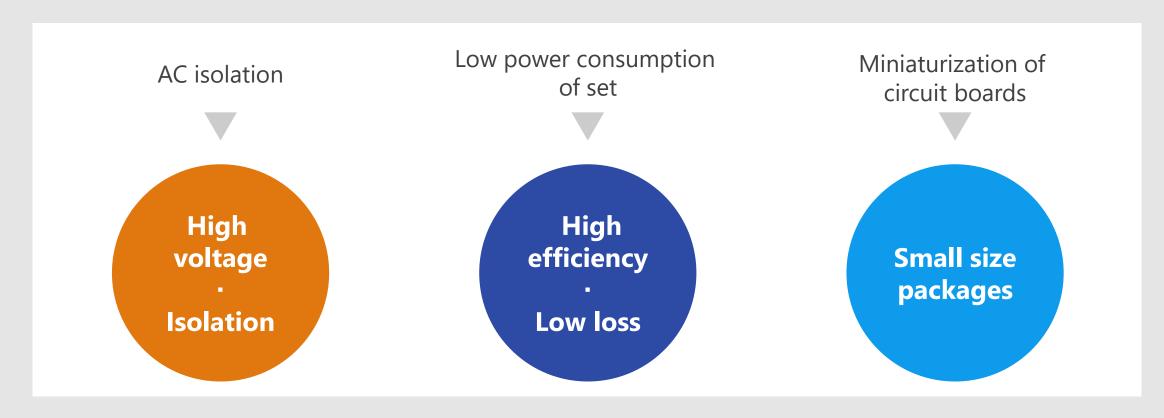


^{*} Click on the blue circled numbers above to view detailed descriptions.



Device solutions to address customer needs

As described above, in the design of Smart Plug, "AC isolation", "Low power consumption of set" and "Miniaturization of circuit boards" are important factors. Toshiba's proposals are based on these three solution perspectives.



Device solutions to address customer needs

	High voltage . Isolation	High efficiency . Low loss	Small size packages
1 TVS diode			
2 Schottky barrier diode			
3 Small signal MOSFET			
4 Photorelay			
5 Photovoltaic output photocoupler	r		
6 DTMOSIV Series MOSFET			
7 Triac output photocoupler			
8 Small surface mount LDO regulate	or		







Absorbs static electricity (ESD) from external terminals, prevents circuit malfunction and protects devices.

Improved ESD absorption

Improved ESD absorption compared to Toshiba's existing products. (50 % reduction in operating resistance)
For some products, both low operating resistance and low capacitance are realized and ensures high signal protection performance and signal quality.

V [V]

2 Suppress ESD energy by low clamp voltage

Protect the connected circuits and devices using Toshiba own technology.

Suitable for high density mounting

A variety of compact packages are available.

ESD Pulse Absorption Performance (Toshiba internal comparison) Latest device (EAP-IV) DF2B5M4SL Toshiba's existing device (EAP-IV) DF2B5M4SL Higher ESD absorption performance than Toshiba's existing device (50% reduction in dynamic resistance) 0 10 20 30 40 50

Unidirectional

Suitable for paths such as logic signals. There are lineups of 1in1, 2in1, 4in1, 5in1, 7in1.

Bidirectional



Suitable for paths with both polar signals such as audio signals.

Lineup							
Part number	DF2B7ASL DF2B5M4SL DF2B6M4SL DF2B6M4BS						
Package		SL2	\rightarrow				
V _{ESD} [kV]	±30	±20	±20	±8			
V _{RWM} (Max) [V]	5.5	3.6	5.5	5.5			
C _t (Typ.) [pF]	8.5	0.2	0.2	0.12			
R _{DYN} (Typ.) [Ω]	0.2	0.5	0.5	1.05			

◆Return to Block Diagram TOP

(Note) This product is an ESD protection diode and cannot be used for purposes other than ESD protection.







The Schottky barrier diode suitable for small equipment applications.

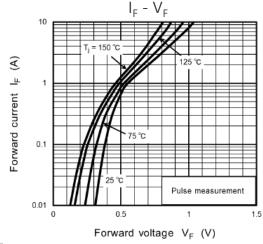
High-speed switching

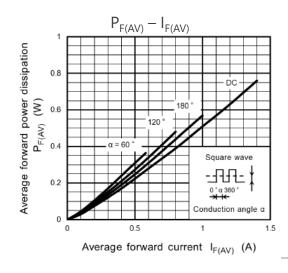
It is suitable for high-speed switching applications.

2 Small package

This small package is suitable for high density mounting.

CRS13 Characteristics Curves





Lineup		
Part number	CRS03	CRS13
Package	S-FLAT™	
V _{RRM} [V]	30	60
I _{F(AV)} [A]	1.0	1.0
V _{FM} (Max) [V]	0.45	0.55
I _{RRM} (Max) [μA]	100	50







Suitable for power switching and contribute to miniaturization.

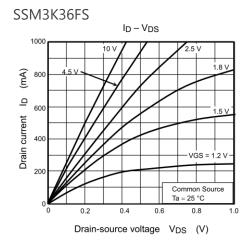
Low voltage operation

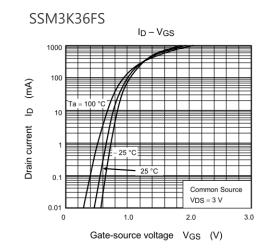
Operates down to $V_{GS} = 1.5 \text{ V}$

2

Low on-resistance

On-resistance between the drain and source is low and heat generation and power consumption can be kept low.





Lineup						
Part number	SSM3K36FS	SSM3K56FS				
Package	SSM	SSM				
V _{DSS} [V]	20	20				
I _D [A]	0.5	0.8				
P _D [W]	0.15	0.15				
$R_{DS(ON)}$ (Max) [Ω] @ V_{GS} = 4.5 V	0.66	0.235				
Polarity	N-ch	N-ch				







Photorelay consists of an infrared light emitting diode optically coupled to a photo-MOSFET and is suitable for replacing mechanical relays.

Low on-resistance

Maximum on-resistance R_{ON} at turn-on is 2Ω (at $I_{ON} = 0.6 A$).

Wide range of ON current

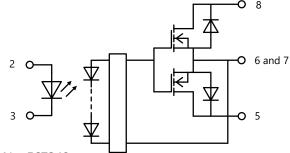
Wide range of allowed ON current I_{ON} , suitable for power line control (maximum 0.6 A : A connected) [Note1]

3 Various lead forming option

Lead forming options (through-hole type and lead forming options. Five total selections) allow design freedom and miniaturization of the set.

[Note1] Please refer to the technical data sheet for connection.

Internal equivalent circuit



UL certified UL1577, File No. E67349

cUL certified CSA Component Acceptance Service No.5A File No. E67349

UL-recognized: UL 508, File No.E499232 [Note2]

VDE-approved: EN 60747-5-5 [Note3]

[Note2] Please refer Absolute Maximum Ratings (UL-recognized UL 508) for UL 508 products.

[Note3] When a VDE approved type is needed, please designate the Option (D4).

Lineup	
Part number	TLP3549
Package	DIP8
V _{OFF} [V]	600
V _{DD} (Max) [V]	480
I _F (Max) [mA]	25
I _{ON} (Max) [A]	0.6
BV _S [Vrms]	2500

5 Photovoltaic output photocoupler







Value provided

Photocoupler consists of an infrared light emitting diode optically coupled to a photo-diode array and is suitable for driving gate of MOSFET.

For MOSFET gate driver

Photodiode is connected in series, suitable for driving the gate of MOSFET.

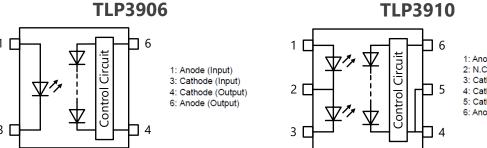
No need to use external discharging resistor

Since the control circuit is on the detector side, there is no need to connect an external discharging resistor.

3 Improved switching speed

Maximum value of t_{on} and t_{off} are 1 ms and 0.5 ms, respectively. (TLP3910)

Internal equivalent circuit



1: Anode (Input) 2: N.C. (Note) 3: Cathode (Input) 4: Cathode (Output) 5: Cathode (Output) 6: Anode (Output)

UL certified UL1577, File No.E67349
cUL certified CSA Component Acceptance Service No.5A File No.E67349
VDE certified EN60747-5-5 (TLP3906/TLP3910), EN62368-1 (TLP3906) [Note]
[Note] To specify a VDE certified model, request a (V4) model

Lineup						
Part number	TLP3906	TLP3910				
Package	4pin SO6	SO6L				
I _F [mA]	30	30				
V _{OC} (Min) [V]	7	14				
I _{SC} (Min) [μΑ]	12	12				
BV _s [Vrms]	3750	5000				
Creepage distance (Min) [mm]	5.0	8.0				







30 % reduction in the figure of merit RonA (compared with Toshiba DTMOSⅢ products), improving power supply efficiency and contributing to miniaturization.

RonA 30 % reduction

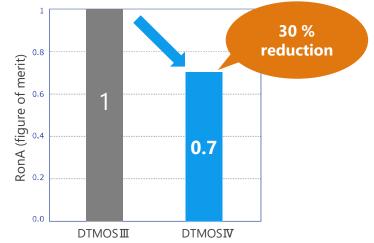
Adoption of the single-epitaxial process to reduce the figure of merit RonA by 30 %. (Compared with DTMOSIII products from Toshiba)

2 Reduction of on-resistance increase at high temperature

The single epitaxial process reduces the on-resistance increase at high temperature.

Optimization of switching speed

Optimization of switching speed has been achieved by reduction of C_{OSS} (by 12 %, compared with Toshiba conventional products) and others.



[Note] Toshiba internal compariso		[Note]	Toshiba	internal	compariso
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Lineup						
Part number	TK8P60W	TK16G60W				
Package	DPAK	D2PAK				
V _{DSS} [V]	600	600				
I _D [A]	8.0	15.8				
P _D [W]	80	130				
C _{iss} (Typ.) [pF]	570	1350				
$R_{DS(ON)}$ (Max) [Ω]	0.5	0.19				
Polarity	N-ch	N-ch				







Photocoupler suitable for AC switching.

Small package (4pin SO6)

Thin 4pin SO6 (3.7 x 7.0 x 2.1 mm) package allows high density mounting.

High isolation voltage (3750 Vrms)

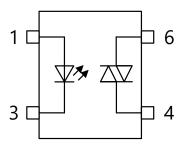
Isolation voltage is 3750 Vrms. Insulator thickness is 0.4 mm, creepage and clearance distances are 5.0 mm. Compliant with reinforced insulation safety standards.

Compatible with zero-cross output

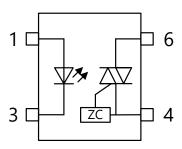
Maximum output current is 70 mA. Higher output is possible using main triac connection. Zero-cross (ZC) compatible output is also available.

Pin layout

TLP265J / TLP267J



TLP266J / TLP268J



- 1. Anode
- 3. Cathode
- 4. Triac pin
- 6. Triac pin

Lineup							
Part number	TLP265J TLP266J TLP267J TLP268J						
Package	4pin SO6						
Output Type	Non-ZC ZC Non-ZC ZC						
V _{DRM} [V]	600						
I _{FT} (Max) [mA]	10 3						
I _{T(RMS)} [mA]	70						
BV _S [Vrms]	3750						







Wide lineup from general purpose type to small package type are provided. Contribute to realize a stable power supply not affected by fluctuation of battery.

Low dropout voltage

The originally developed the latest generation process significantly improved the dropout voltage characteristics.

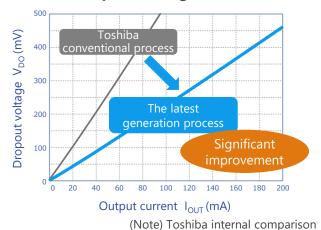
High PSRR Low output noise voltage

Many product series that realize both high PSRR (Power Supply Rejection Ratio) and low output noise voltage characteristics are provided. They are suitable for stable power supply for analog circuit.

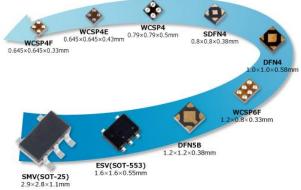
3 Low current consumption

 $0.34~\mu A$ of $I_{B(ON)}$ is realized by utilizing CMOS process and unique circuit technology. (TCR3U Series)

Low dropout voltage



Rich package lineup



Lineup	Lineup								
Part number	TCR15AG Series	TCR13AG Series	TCR8BM Series	TCR5BM Series	TCR5RG Series	TCR3RM Series	TCR3U Series	TCR2L Series	TAR5 Series
Features			out voltage PSRR		Low Low c	PSRR noise urrent mption		urrent mption	15 V Input voltage Bipolar type
I _{OUT} (Max) [A]	1.5	1.3	0.8	0.5		.5 0.3			0.2
PSRR (Typ.) [dB] @f = 1 kHz	95	90	98	98	100	100	70	-	70
I _B (Typ.) [μΑ]	25	56	20	19	7	7	0.34	1	170

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